

WHAT IS CLAIMED IS:

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5 1. A printed wiring board with an electronic component face-mounted on a circuit board in which the electronic component is provided with a heat radiating plate for conducting heat internally generated, comprising:

heat radiating means face-mounted at a position corresponding to the electronic component on a rear surface of the circuit board.

10 2. A printed wiring board according to claim 1, wherein said heat radiating means is soldered on said circuit board.

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15 3. A printed wiring board according to claim 2, wherein said heat radiating means has a plated layer so that it can be soldered to said circuit board through the plated layer.

4. A printed wiring board according to claim 3, wherein said plated layer contains tin.

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20 5. A printed wiring board according to claim 3, wherein said plated layer contains nickel.

6. A printed wiring board according to any one of claims 1, wherein said heat radiating means is made of metal, and is
25 provided, on a rear side thereof, with an attaching plate which

can be brought into face-contact with said circuit board on a rear side thereof and on a front side thereof, with a plurality of fins for radiating heat.

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- 5 7. A printed wiring board according to claim 6, wherein said heat radiating means is formed in such a way that a corrugated member having a uniform section extruded from long-lengths of a belt-shaped hoop material is cut at prescribed lengths.

- 10 8. A printed wiring board according to claim 1, wherein a first heat radiating pattern for conducting heat is formed at a position on a front surface of said circuit board corresponding to said electronic component, and said heat radiating plate of the electronic component is connected to
15 said first heat radiating pattern by soldering.

- 20 9. A printed wiring board according to any one of claims 1, wherein a second heat radiating pattern for conducting heat is formed at a position on a rear surface of said circuit board corresponding to said electronic component, and said heat radiating means is mounted on said circuit board in such a way that said second heat radiating pattern is soldered to its attaching face.

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- 25 10. A printed wiring board according to claim 9, wherein said

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first heat radiating pattern and said heat radiating pattern are connected to each other via through-holes which passing through said circuit board.

5 11. A printed wiring board according to claim 8, wherein said first heat radiating pattern is a common pattern of wiring patterns which constitute circuits formed on said circuit board.

10 12. A printed wiring board according to claim 9, wherein said first heat radiating pattern is a common pattern in wiring patterns which constitute circuits formed on said circuit board.

15 13. A printed wiring board according to claim 6, wherein said heat radiating means is attached to said circuit board in such a manner that said fins stand when the circuit board is used in its standing state.

20 14. A printed wiring board according to claim 10, wherein said first heat radiating pattern and said second heat radiating pattern are connector are connected via the through hole in heat, and inner surface of the through hole are covered with a material having a specific heat smaller than that of
25 the printed wiring board.